| ASSOCIATION CONNECTING<br>ASSOCIATION CONNECTING<br>ELECTRONICS INDUSTRIES®<br>international and Par | PC. Bannock  | burn, Illinois, A       | ll rights reserved nations. | under both              | This docume<br>level parts, t   | ent is a declaration entite declaration entite | on of the su     | bstances v<br>s all lower | vithin the manufactule level materials for v | urer listed which the   | item. Note:<br>manufactur       | if the item is an as<br>er has engineering | sembly with low responsibility. |  |
|--|--------------|-------------------------|-----------------------------|-------------------------|---|--|------------------|---------------------------|--|-------------------------|---------------------------------|--|---------------------------------|--|
|  |              |                         |                             | Form Type<br>Distribute | * Declaration Class *<br>Class 6 - RoHS Yes/No, Homogeneous Materials and |  |                  |                           |  | rials and N             | Ifg Informa                     | ation                                      |                                 |  |
| Supplier Information   |              |                         |                             |                         |   |  |                  |                           |  |                         |                                 |  |                                 |  |
| Company name* Co   |              |                         | Company unique ID           |                         |   | Unique ID Authority                            |                  |                           |  | Respor                  | Response Date*                  |  |                                 |  |
| nsemi  |              |                         |                             |                         |   |  |                  |                           | 2024-05-07                                   |                         |                                 |  |                                 |  |
| Contact Name Title - Contact   |              |                         | et                          | F                       |   |  | Phone - Contact* |                           |  |                         | Email - Contact*                |  |                                 |  |
| Product-Env-Stewards Product Env   |              |                         | nviro Compliance            |                         |   | NA   |                  |                           |  | Produ                   | Product-Env-Stewards@onsemi.com |  |                                 |  |
| Authorized Representative* Title - Represe   |              |                         | sentative                   |                         |   | Phone - Representative*                        |                  |                           | Email  | Email - Representative* |                                 |  |                                 |  |
| Product-Env-Stewards Product En  |              |                         | uct Enviro Compliance       |                         |   | NA   |                  |                           |  | Produ                   | Product-Env-Stewards@onsemi.com |  |                                 |  |
| Requester Item Number  | Mfr Iter     | n Number                | Mfr Item Name               |                         |   | Effective Date                                 | Version          | М                         | Manufacturing Site                           |                         | Weight*                         | UOM  | Unit Type                       |  |
|  | MC74L<br>2G  |                         |                             | RNSCIEVR DUAL           |   | 2024-05-07                                     |                  | PI                        | PH1  |                         | 661.78                          | mg   | Each                            |  |
| Aanufacturing Proccess Informa   | tion         |                         |                             |                         |   |  |                  |                           |  |                         |                                 |  |                                 |  |
| Terminal Plating / Grid Array Ma   | aterial '    | ial Terminal Base Alloy |                             | J-STD-020 MSL Rating    |   | Peak Process Body Temperat                     |                  | emperature                | ure Max Time at Peak Temper                  |                         | ture Num                        | nber of Reflow Cyc                         | les                             |  |
| Matte Tin (Sn) - annealed CU Alloy   |              | CU Alloy                |                             | 3                       |   | <b>260</b> C                                   |                  | С                         | 30   | seco                    | nds 3                           |  |                                 |  |
| omments  |              |                         |                             |                         |   |  |                  |                           |  |                         |                                 |  |                                 |  |
| TTENTION: MSL 3 Rated item require   | s Bake and I | Dry Pack (after         | electrical test)            |                         |   |  |                  |                           |  |                         |                                 |  |                                 |  |
| or more information regarding material   | composition  | please refer to         | page 3                      |                         |   |  |                  |                           |  |                         |                                 |  |                                 |  |

| RoHS Material Composition Declaration  |  |  |   | Declaration Type *                              | Detailed  |  |  |  |  |  |  |
|--|--|--|---|---|---|--|--|--|--|--|--|
| Directive 2015/863/EU amending RoHS<br>Directive 2011/65/EU  | RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Disobutyl phthalate (DIBP). |  |   |   |   |  |  |  |  |  |  |
| cadmium, hexavalentchromium, polybrominate<br>contains a RoHS restricted substance inexcess<br>encompass all such components. Supplier certif<br>as of the date that Supplier completes this form<br>Company acknowledges that Supplier may hav<br>independently verified information provided by<br>certification in this paragraph. If the Company a | ed biphenyls and/or polybrominated dip<br>of an applicable quantity limit, please ir<br>ies that it gathered the information it pro-<br>.Supplier acknowledges that Company<br>e relied on informationprovided by othe<br>y others, Supplier agrees that, at a minin<br>and the Supplier enter into a written agre<br>pource of the Supplier's liability and the   | henyl ethers (each a "<br>ndicate below which, i<br>ovides in this form us<br>will rely on this certifiers<br>in completing this<br>num, itssuppliers have<br>eement with respect to<br>Company's remedies | RoHS restricted substance") in exce<br>if any, RoHS exemption you believe<br>ing appropriate methods to ensure if<br>ication in determining the complian<br>form, and that Supplier may not have<br>e provided certifications regarding the<br>to the identified part, the terms and cc<br>for issues that arise regarding inform | ce of its products with European Union membe    | ove. If a homogeneous material within the part<br>er level components, the declaration shall<br>l correct to the best of its knowledge and belief,<br>r state laws that implement the RoHS Directive.<br>wever, in situations where Supplier has not<br>tions are at least as comprehensive as the<br>anty rights and/or remedies provided as part of |  |  |  |  |  |  |
| RoHS Declaration * 1 - Item(s)   | does not contain RoHS restricted substa  | ances per the definitio  | on above  | Supplier Acceptance                             | * Accepted  |  |  |  |  |  |  |
| Exemption: If the declared item does not con applicable exemptions.  | ntain RoHS restricted substances per   | the definition above   | except for defined RoHS exempti   | ons, then select the corresponding response i   | n the RoHS Declaration above and choose all   |  |  |  |  |  |  |
| Exemption List Version   | EL-2011/534/EU   |  |   |   |   |  |  |  |  |  |  |
| Declaration Signature  |  |  |   |   |   |  |  |  |  |  |  |
| Instructions: Complete all of the required fin<br>Requester) and click on Submit Form to have  | elds on all pages of this form. Select the form returned to the Requester  | he "Accepted" on th  | e Supplier Acceptance drop-down   | . This will display the signature area. Digital | lly sign the declaration (if required by the  |  |  |  |  |  |  |
| Supplier Digital Signature Ra  | stislav Drska  | Le   |   |   |   |  |  |  |  |  |  |

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

| Homogeneous Material | Weight | Unit of Measure | Level    | Substance           | CAS              | Exempt | Weight   | Unit of Measure |
|----------------------|--------|-----------------|----------|---------------------|------------------|--------|----------|-----------------|
| Die                  | 3.79   | mg              | Supplier | Silicon (Si)        | 7440-21-3        |        | 3.79     | mg              |
| Die Attach           | 24.58  | mg              | Supplier | Silver (Ag)         | 7440-22-4        |        | 18.435   | mg              |
|                      |        |                 | Supplier | Epoxy resins        | 129915-35-1      |        | 6.145    | mg              |
| Lead Frame           | 385.08 | mg              | Supplier | Silver (Ag)         | 7440-22-4        |        | 2.6956   | mg              |
|                      |        |                 | Supplier | Zinc (Zn)           | 7440-66-6        |        | 0.4621   | mg              |
|                      |        |                 | Supplier | Iron (Fe)           | 7439-89-6        |        | 9.0494   | mg              |
|                      |        |                 | Supplier | Copper (Cu)         | 7440-50-8        |        | 372.7574 | mg              |
|                      |        |                 | Supplier | Phosphorus (P)      | 7723-14-0        |        | 0.1155   | mg              |
| Mold Compound-Black  | 242.16 | mg              |          | Epoxy Phenol Resin  | proprietary data |        | 25.4268  | mg              |
|                      |        |                 | Supplier | Fused Silica (SiO2) | 60676-86-0       |        | 216.7332 | mg              |
| Plating              | 5.6    | mg              | Supplier | Tin (Sn)            | 7440-31-5        |        | 5.6      | mg              |
| Wire Bond - Au       | 0.57   | mg              | Supplier | Gold (Au)           | 7440-57-5        |        | 0.57     | mg              |